

Thermal Properties of Materials

Topics included:

- How do materials respond to the application of heat?
- How do we define and measure...
 - heat capacity and specific heat?
 - thermal expansion?
 - thermal conductivity?
 - thermal shock resistance?
- Mechanism of heat absorption in solids.
- Difference between the thermal properties of ceramics, metals, and polymers?

What is meant by thermal properties of materials

- Thermal property refers to the response of a material to the application of heat.
- When solid absorbs energy in the form of heat, its temperature rises and its dimensions increase.
- The energy may be transported to cooler regions of the specimen if temperature gradients exist, and ultimately, the specimen may melt.
- Heat capacity, thermal expansion, and thermal conductivity are properties that are often critical in the practical use of solids.

Heat Capacity

The ability of a material to absorb heat, i.e.

- the amount of energy required to produce a unit temperature rise

The diagram shows the equation $C = \frac{dQ}{dT}$ enclosed in a yellow box. A blue arrow points from the text 'heat capacity (J/mol-K)' to the variable C , which is highlighted in a light blue box. A red arrow points from the text 'energy input (J/mol)' to the numerator dQ , which is highlighted in a light red box. A green arrow points from the text 'temperature change (K)' to the denominator dT , which is highlighted in a light green box.

- Two ways to measure heat capacity:

C_p : Heat capacity at constant pressure.

C_v : Heat capacity at constant volume.

C_p usually $> C_v$

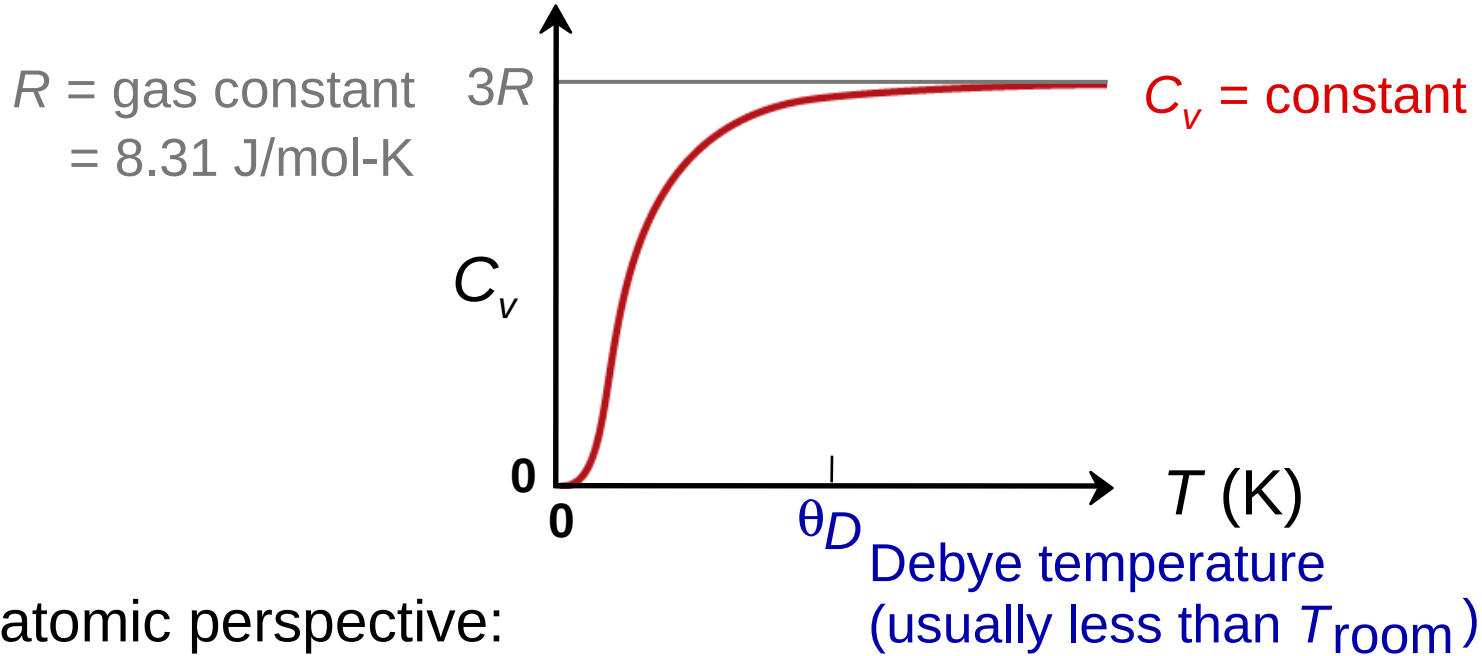
- Heat capacity has units of $\frac{\text{J}}{\text{mol} \cdot \text{K}} \left(\frac{\text{Btu}}{\text{lb} - \text{mol} \cdot ^\circ\text{F}} \right)$

Specific Heat

- Often denoted by a lowercase c
- this represents the heat capacity per unit mass
- units ($\text{J/kg} \cdot \text{K}$, $\text{cal/g} \cdot \text{K}$)

Dependence of Heat Capacity on Temperature

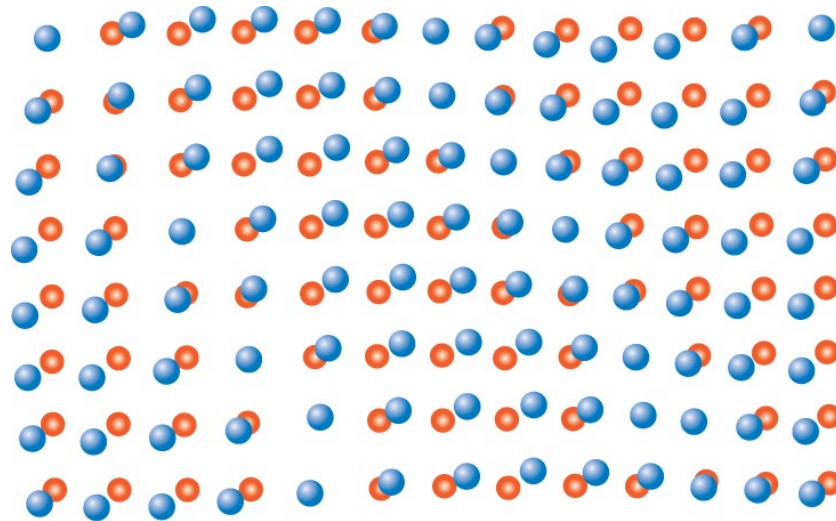
- Heat capacity...
 - increases with temperature
 - for solids it reaches a limiting value of $3R$



- From atomic perspective:
 - Energy is stored as atomic vibrations.
 - As temperature increases, the average energy of atomic vibrations increases.


Atomic Vibrations

- Vibrational Heat Capacity
- Atoms in solid materials are constantly vibrating at very high frequencies and with relatively small amplitudes.
- Atomic vibrations are in the form of elastic waves
- Single quantum of vibrational energy is called a **phonon**



- Normal lattice positions for atoms
- Positions displaced because of vibrations

Specific Heat: Comparison



Material	c_p (J/kg-K) at room T
• <u>Polymers</u>	
Polypropylene	1925
Polyethylene	1850
Polystyrene	1170
Teflon	1050
• <u>Ceramics</u>	
Magnesia (MgO)	940
Alumina (Al ₂ O ₃)	775
Glass	840
• <u>Metals</u>	
Aluminum	900
Steel	486
Tungsten	138
Gold	128

c_p (specific heat): (J/kg-K)

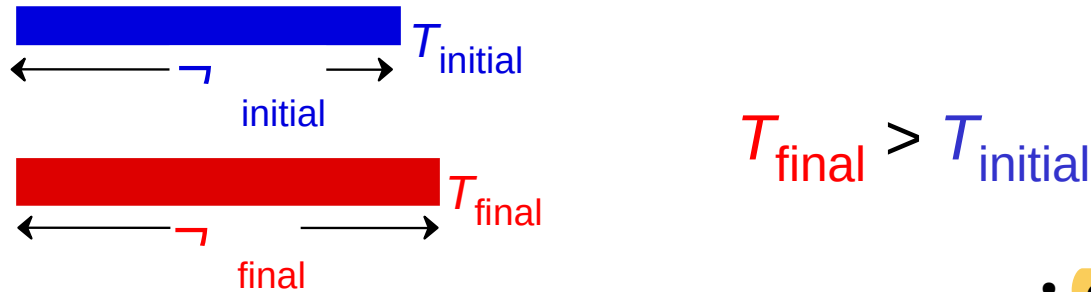
C_p (heat capacity): (J/mol-K)

- Why is c_p significantly larger for polymers?

Thermal Expansion

Materials change size when temperature is changed

✓ Most solid materials expand upon heating and contract when cooled.

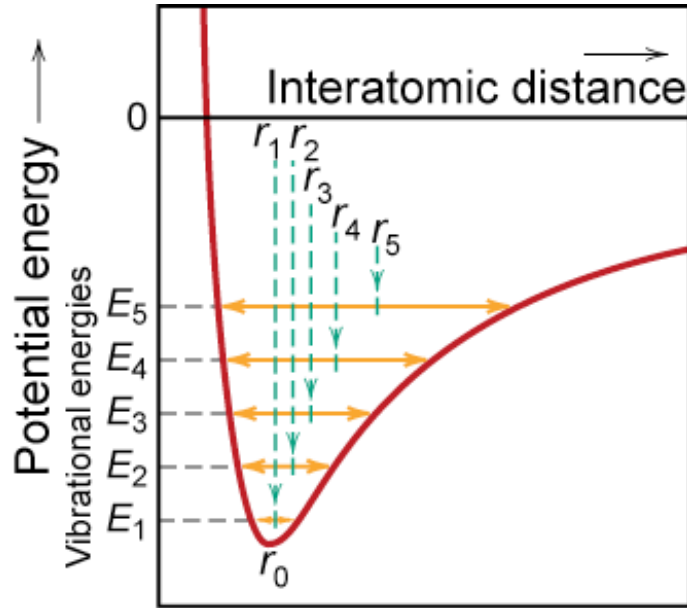


$$\frac{l_{\text{final}} - l_{\text{initial}}}{l_{\text{initial}}} = \alpha_l (T_{\text{final}} - T_{\text{initial}})$$

linear coefficient of
thermal expansion ($1/\text{K}$ or $1/^\circ\text{C}$)

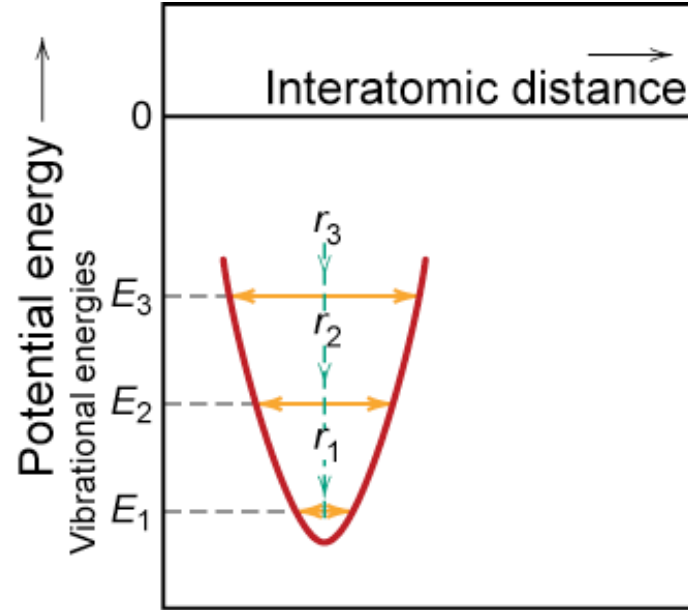
- α – a material property
- extent to which a material expands upon heating
- units of reciprocal temperature [$(^\circ\text{C})^{-1}$ or $(^\circ\text{F})^{-1}$]

Atomic Perspective: Thermal Expansion



Asymmetric curve:


- increase temperature,
- **increase in interatomic separation**
- **contributes to thermal expansion**



Symmetric curve:

- increase temperature,
- **no increase in interatomic separation**
- **no thermal expansion**

Coefficient of Thermal Expansion: Comparison



Material	α ($10^{-6} (^{\circ}\text{C})^{-1}$) at room T
• <u>Polymers</u>	
Polypropylene	145-180
Polyethylene	106-198
Polystyrene	90-150
Teflon	126-216
• <u>Metals</u>	
Aluminum	23.6
Steel	12
Tungsten	4.5
Gold	14.2
• <u>Ceramics</u>	
Magnesia (MgO)	13.5
Alumina (Al_2O_3)	7.6
Soda-lime glass	9
Silica (cryst. SiO_2)	0.4

Polymers have larger α values because of weak secondary bonds

Q: Why does α generally decrease with increasing bond energy?

Thermal Expansion: Example

Example: A copper wire 15 m long is cooled from 40 to -9°C. How much change in length will it experience?

- For Cu $\alpha_{\ell} = 16.5 \times 10^{-6} (\text{°C})^{-1}$

Thermal Expansion: Example

Example: A copper wire 15 m long is cooled from 40 to -9°C. How much change in length will it experience?

- Answer: For Cu $\alpha_{\ell} = 16.5 \times 10^{-6} (^{\circ}\text{C})^{-1}$

$$\Delta \ell = \alpha_{\ell} \ell_0 \Delta T = [16.5 \times 10^{-6} (1/^{\circ}\text{C})](15 \text{ m})[40^{\circ}\text{C} - (-9^{\circ}\text{C})]$$

$$\Delta \ell = 0.012 \text{ m} = 12 \text{ mm}$$

Thermal Conductivity

The ability of a material to transport heat.

Fourier's Law

$$\text{heat flux (J/m}^2\text{/s)} \rightarrow q = -k \frac{dT}{dx}$$

temperature gradient

thermal conductivity (Unit?)



- Atomic perspective: Atomic vibrations and free electrons in hotter regions transport energy to cooler regions.


Thermal Conductivity

The ability of a material to transport heat.

Fourier's Law

heat flux (J/m²/s) $\rightarrow q = -k \frac{dT}{dx}$ temperature gradient

thermal conductivity (J/(m.s.K))



The diagram illustrates a horizontal bar of material. The left end is at position x_1 with temperature T_1 , and the right end is at position x_2 with temperature T_2 . A large red arrow labeled "heat flux" points from right to left, indicating the direction of heat transport. To the right of the bar, the condition $T_2 > T_1$ is noted. The equation $q = -k \frac{dT}{dx}$ is shown above the bar, with arrows pointing from the labels to the corresponding terms: "heat flux" to q , "thermal conductivity" to k , and "temperature gradient" to $\frac{dT}{dx}$.

- Atomic perspective: Atomic vibrations and free electrons in hotter regions transport energy to cooler regions.

Mechanisms of Heat Conduction

In solid materials,

- heat is transported by both lattice vibration waves (phonons) and free electrons.
- Thermal conductivity is associated with each of these mechanisms,
- Total conductivity is the sum of the two contributions,

$$k = k_l + k_e$$

- Thermal energy associated with phonons or lattice waves is transported in the direction of their motion.
- The k_l contribution results from a net movement of phonons from high- to low-temperature regions of a body across which a temperature gradient exists.

Metals

- the electron mechanism of heat transport is much more efficient than the phonon contribution because electrons are not as easily scattered as phonons and have higher velocities.
- relatively large numbers of free electrons exist that participate in thermal conduction.
- Because free electrons are responsible for both electrical and thermal conduction in pure metals, the two conductivities should be related.
- According to the Wiedemann–Franz law:

$$L = \frac{k}{\sigma T}$$

where σ is the electrical conductivity,
T is the absolute temperature, and

L is a constant, known as Lorenz number with a theoretical value of $2.44 \times 10^{-8} \text{ V}^2/\text{K}^2$, should be independent of temperature and the same for all metals if the heat energy is transported entirely by free electrons.


Ceramics

- they lack large numbers of free electrons
- the phonons are primarily responsible for thermal conduction:
- k_e is much smaller than k_l
- phonons are not as effective as free electrons in the transport of heat energy as a result of the very efficient phonon scattering by lattice imperfections.
- phonon scattering is much dominant when the atomic structure is highly disordered and irregular.
- Porosity in ceramic materials may have a dramatic influence on thermal conductivity;
- Increasing the pore volume results in a reduction of the thermal conductivity.

Polymers

- Energy transfer is accomplished by the vibration and rotation of the chain molecules.
- The magnitude of the thermal conductivity depends on the degree of crystallinity;
- a polymer with a highly crystalline and ordered structure has a greater conductivity than the equivalent amorphous material

Thermal Conductivity: Comparison



Material	k (W/m-K)	Energy Transfer Mechanism
• <u>Metals</u>		
Aluminum	247	atomic vibrations and motion of free electrons
Steel	52	
Tungsten	178	
Gold	315	
• <u>Ceramics</u>		
Magnesia (MgO)	38	atomic vibrations
Alumina (Al ₂ O ₃)	39	
Soda-lime glass	1.7	
Silica (cryst. SiO ₂)	1.4	
• <u>Polymers</u>		
Polypropylene	0.12	vibration/rotation of chain molecules
Polyethylene	0.46-0.50	
Polystyrene	0.13	
Teflon	0.25	

Thermal Stresses

- Occur due to:
 - restrained thermal expansion/contraction
 - temperature gradients that lead to differential dimensional changes
 - May result in fracture or undesirable plastic deformation.

Thermal stress

$$\sigma = E\alpha_l (T_0 - T_f) = E\alpha_l \Delta T$$

→ cooling

$T_f - T_0 \longrightarrow$ heating

Upon heating ($T_f > T_0$), the stress is compressive ($\sigma < 0$) because rod expansion has been constrained.

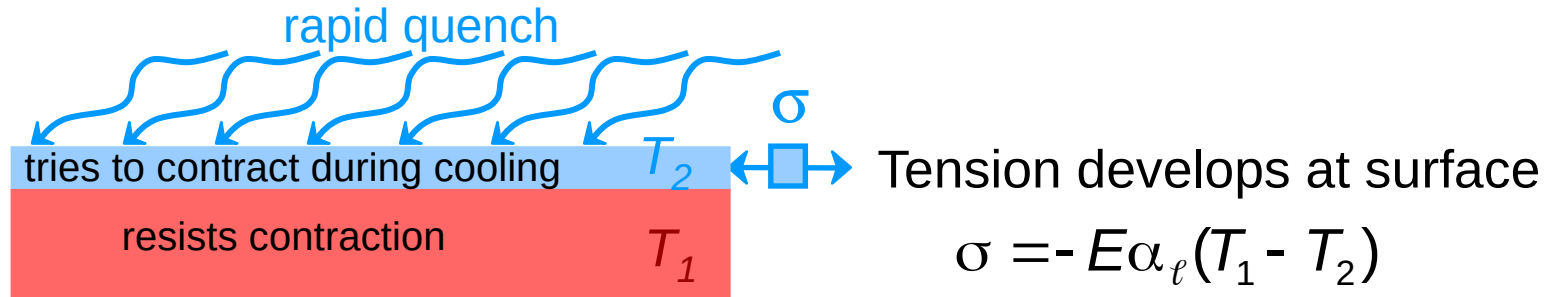
If the rod specimen is cooled ($T_f < T_0$), a tensile stress is imposed ($\sigma > 0$).

Example:

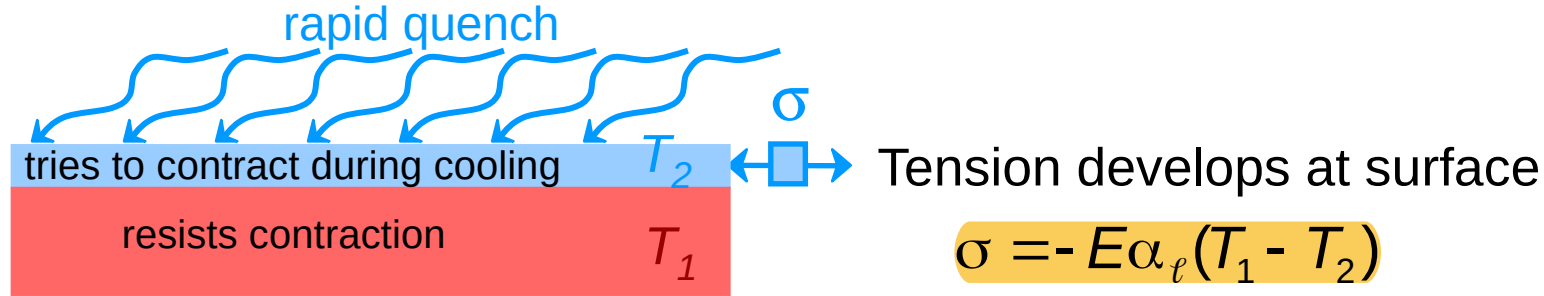
- A brass rod is stress-free at room temperature (20°C).
- It is heated up, but held rigidly to the clamps.
- At what temperature does the *compressive* stress reach 172 Mpa?
- Assume a modulus of elasticity of 100 GPa for brass.
- linear coefficient of thermal expansion for brass: $20.0 \times 10^{-6} (\text{°C})^{-1}$

Thermal Shock Resistance

- Occurs due to: nonuniform heating/cooling
- Ex: Assume top thin layer is rapidly cooled from T_1 to T_2



Thermal Shock Resistance



$$\sigma = -E\alpha_{\ell}(T_1 - T_2)$$

Temperature difference that can be produced by cooling:

$$(T_1 - T_2) = \frac{\text{quench rate}}{k}$$

Critical temperature difference for fracture (set $\sigma = \sigma_f$)

$$(T_1 - T_2)_{\text{fracture}} = \frac{\sigma_f}{E\alpha_{\ell}}$$

set equal

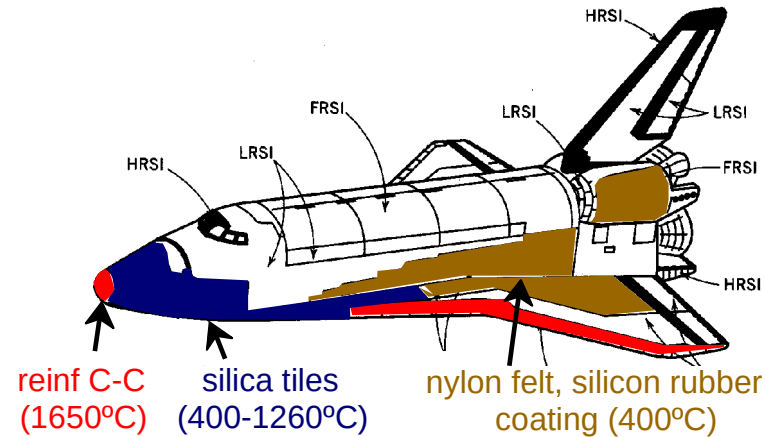
- (quench rate)_{for fracture} = Thermal Shock Resistance (TSR) $\propto \frac{\sigma_f k}{E\alpha_{\ell}}$
- Large TSR when $\frac{\sigma_f k}{E\alpha_{\ell}}$ is large

Thermal Protection Systems prevalent for different
kind of materials

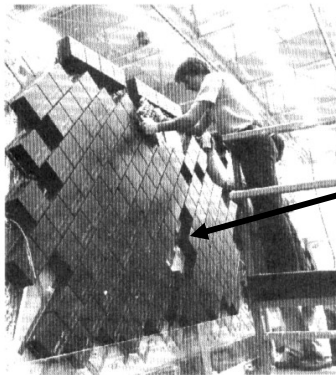
Thermal Protection System

- Application:

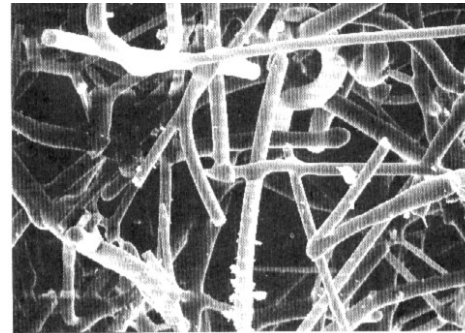
Space Shuttle Orbiter



- Silica tiles** (400-1260°C):
 - large scale application



-- microstructure:



100 μm

~90% porosity!
Si fibers
bonded to one
another during
heat treatment.

Summary

The thermal properties of materials include:

- **Heat capacity:**
 - energy required to increase a mole of material by a unit T
 - energy is stored as atomic vibrations
- **Coefficient of thermal expansion:**
 - the size of a material changes with a change in temperature
 - polymers have the largest values
- **Thermal conductivity:**
 - the ability of a material to transport heat
 - metals have the largest values
- **Thermal shock resistance:**
 - the ability of a material to be rapidly cooled and not fracture

- is proportional to $\frac{\sigma_f k}{E \alpha_f}$